# **Quad 2-Input AND Gate**

The MC10104 is a quad 2-input AND gate. One of the gates has both AND/NAND outputs available.

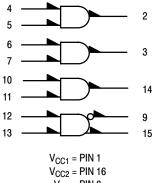
- $P_D = 35 \text{ mW typ/gate (No Load)}$
- $t_{pd} = 2.7 \text{ ns typ}$
- $t_r$ ,  $t_f = 2.0$  ns typ (20%–80%)

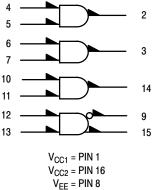


# ON Semiconductor

http://onsemi.com

### **LOGIC DIAGRAM**





# **MARKING DIAGRAMS**

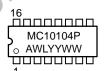


CDIP-16 **L SUFFIX CASE 620** 





PDIP-16 P SUFFIX **CASE 648** 





PLCC-20 **FN SUFFIX** 





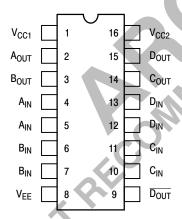
**CASE 775** 

= Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

## DIP **PIN ASSIGNMENT**



Pin assignment is for Dual-in-Line Package. For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

# **ORDERING INFORMATION**

Device	Package	Shipping
MC10104L	CDIP-16	25 Units / Rail
MC10104P	PDIP-16	25 Units / Rail
MC10104FN	PLCC-20	46 Units / Rail

# **ELECTRICAL CHARACTERISTICS**

							Test Limits	<u>;                                    </u>			
Characteristic Syn		Pin Under	−30°C			+25°C		+85°C		1	
		Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply	Drain Current	Ι <sub>Ε</sub>	8		39			35		39	mAdc
Input Current		I <sub>inH</sub> *	12 13		425 350			265 220		265 220	μAdc
		I <sub>inL</sub>	12	0.5		0.5			0.3		μAdc
Output Voltage	e Logic 1	V <sub>OH</sub>	15 9	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdc
Output Voltage	e Logic 0	V <sub>OL</sub>	15 9	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vdc
Threshold Vol	tage Logic 1	V <sub>OHA</sub>	9 9 15 15	-1.090 -1.090 -1.090 -1.090		-0.980 -0.980 -0.980 -0.980			-0.910 -0.910 -0.910 -0.910	C	Vdc
Threshold Vol	tage Logic 0	V <sub>OLA</sub>	9 9 15 15		-1.655 -1.655 -1.655 -1.655			-1.630 -1.630 -1.630 -1.630		-1.595 -1.595 -1.595 -1.595	Vdc
Switching Tim	es (50Ω Load)										ns
Propagation D	Delay	t <sub>12+15+</sub> t <sub>12-15-</sub> t <sub>12+9-</sub> t <sub>12-9+</sub>	15 15 9 9	1.0 1.0 1.0 1.0	4.3 4.3 4.3 4.3	1.0 1.0 1.0 1.0	2.2 2.2 2.2 2.2	4.0 4.0 4.0 4.0	1.0 1.0 1.0 1.0	4.2 4.2 4.2 4.2	
		t <sub>13+15+</sub> t <sub>13+9-</sub>	15 9	1.0	4.3 4.3	1,0 1.0	2.7 2.7	4.0 4.0	1.0 1.0	4.2 4.2	
Rise Time	(20 to 80%)	t <sub>15+</sub> t <sub>9+</sub>	15 9	1.5 1.5	3.7 3.7	1.5 1.5	2.0 2.0	3.5 3.5	1.5 1.5	3.6 3.6	
Fall Time	(20 to 80%)	t <sub>15-</sub> t <sub>9-</sub>	15 9	1.5 1.5	3.7 3.7	1.5 1.5	2.0 2.0	3.5 3.5	1.5 1.5	3.6 3.6	

<sup>\*</sup> Inputs 4, 7, 10 and 13 will behave similarly for ac and I<sub>inH</sub> values. Inputs 5, 6, 11 and 12 will behave similarly for ac and I<sub>inH</sub> values.

# **ELECTRICAL CHARACTERISTICS** (continued)

					TEST VOI	TAGE VALU	JES (Volts)		
		@ Test Te	mperature	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	
			–30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
Pin			TEST VOLTAGE APPLIED TO PINS LISTED BELOW						
Characteristic		Symbol	Under Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	(V <sub>CC</sub> ) Gnd
Power Supply Drain (	Current	ΙE	8					8	1, 16
Input Current		I <sub>inH*</sub>	12 13	12, 13 13				8 8	1, 16 1, 16
		I <sub>inL</sub>	12		12			8	1, 16
Output Voltage	Logic 1	V <sub>OH</sub>	15 9	12, 13				8 8	1, 16 1, 16
Output Voltage	Logic 0	V <sub>OL</sub>	15 9	12, 13				8 8	1, 16 1, 16
Threshold Voltage	Logic 1	V <sub>OHA</sub>	9 9 15 15	12 13		13 12	12 13	8 8 8 8	1, 16 1, 16 1, 16 1, 16
Threshold Voltage	Logic 0	V <sub>OLA</sub>	9 9 15 15	12 13		13 12	12 13	8 8 8	1, 16 1, 16 1, 16 1, 16
Switching Times	(50Ω Load)			+1.11V		Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay		t <sub>12+15+</sub> t <sub>12-15-</sub> t <sub>12+9-</sub> t <sub>12-9+</sub>	15 15 9 9	13 13 13 13	(D)	12 12 12 12	15 15 9 9	8 8 8	1, 16 1, 16 1, 16 1, 16
		t <sub>13+15+</sub> t <sub>13+9-</sub>	15 9	12 12		13 13	15 9	8 8	1, 16 1, 16
Rise Time	(20 to 80%)	t <sub>15+</sub> t <sub>9+</sub>	15 9	12 12		13 13	15 9	8 8	1, 16 1, 16
Fall Time	(20 to 80%)	t <sub>15-</sub>	15 9	12 12		13 13	15 9	8 8	1, 16 1, 16

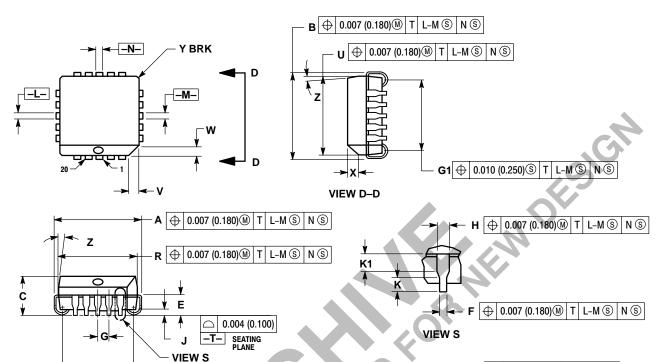
 $<sup>^{\</sup>star}$  Inputs 4, 7, 10 and 13 will behave similarly for ac and  $I_{\rm inH}$  values. Inputs 5, 6, 11 and 12 will behave similarly for ac and  $I_{\rm inH}$  values.

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

#### PACKAGE DIMENSIONS

### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



#### NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF VICE NOT PRESCO

- IOTES:

  1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

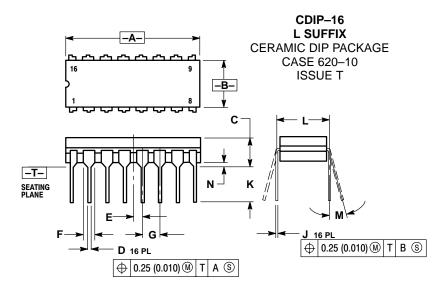
  4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT

INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

#### PACKAGE DIMENSIONS



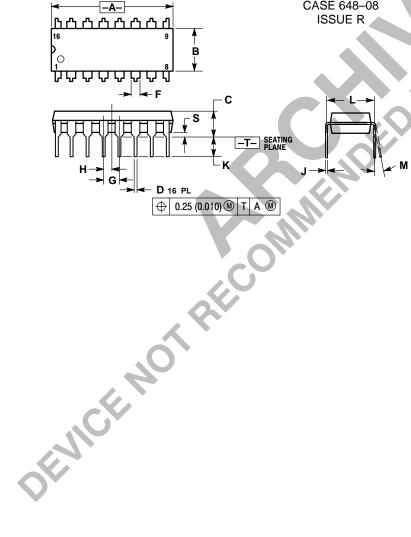
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL
   DIMENSION F MAY NARROW TO 0.76 (0.030)
   WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIMETERS		
DIM	MIN			MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015 0.020		0.39 0.50		
E	0.050	BSC	1.27 BSC		
F	0.055	0.055 0.065		1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62	BSC	
M	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

# PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN MAX		MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.015 0.021		0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

# **Notes**



# **Notes**





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